



AF 3700

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: David M. Curran, et al.
Serial No: 10/029,788
Examiner: Timothy V. Eley
Filed: 10/26/2001

Docket No: TI-29038
Conf. No: 5683
Art Unit: 3724

For: METHOD FOR REDUCING THE THICKNESS OF SPIN-ON GLASS ON
SEMICONDUCTOR WAFERS

AMENDMENT PURSUANT TO 37 CFR 1.116

Mail Stop AF
Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

OK to Enter
02/20/04 On Appeal
Dear Sir:

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MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on 1-29-04.

Ann Trent
Ann Trent

Responsive to the Office Action mailed December 31, 2003, in connection with the above identified application, Applicants respectfully submit the following remarks.

Amendments to the Specification:

None